



Final Product/Process Change Notification

Document #:FPCN22935XB

Issue Date:15 Apr 2020

Title of Change:	Qualification of ON Semiconductor Shenzhen, China as Manufacturing Site for Power Integrated Module (PIM) Products.
Proposed First Ship date:	22 Jul 2020 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or Way-Shan.Yong@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or PCN.samples@onsemi.com Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Phine.Guevarra@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	No change in product marking
Change Category:	Assembly Change
Change Sub-Category(s):	Manufacturing Site Addition

Sites Affected:**ON Semiconductor Sites**

ON Semiconductor Shenzhen, China

External Foundry/Subcon Sites

None

Description and Purpose:

This FPCN announces change of assembly site for affected OPN list to improve manufacturing efficiency.

The change is planned in transferring PIM production from ON Semiconductor Seremban, Malaysia to ON Semiconductor Shenzhen, China.

ON Semiconductor Shenzhen, China is a qualified assembly and test site for PIM module.

Upon the expiration of this PCN, OPNs in affected part list will be assemble/test at ON Semiconductor Shenzhen, China primarily.

This product will be qualified to industrial requirements.

	Before Change Description	After Change Description
Assembly Site	ON Semi Seremban only	ON Semi Shenzhen only

There are no product material changes as a result of this change.

There is no product marking change as a result of this change.

**Reliability Data Summary:**

QV DEVICE NAME : SNXH75M65L3F2STG (Module Qualification), FE6575 (Die Qualification)

RMS : S64115/S64116/V65421/U64962/S64086

PACKAGE : F2

Test	Specification	Condition	Interval	Result
TC	JESD22-A104 cond. G, soak mode 4	Tmin = -40°C, Tmax = 125°C, cycles = 100cyc Dwell time 30min, Transition time 20min max in one chamber equip.	100cyc	0/11
THU	JESD22-A101	T = 85°C, RH = 85%, time = 1008 hours	1008 hours	0/11
H3TRB	JESD22 A101	T = 85°C, RH = 85%, time = 1000 hours, VCE = 0.8Vces =<100V, VGE = 0V	1008 hours	0/11
HTRB	JESD22-A108	Tj=150C, VCE = 80%Vces, VGE = 0V	1008 hours	0/11
VVF	JESD22-B103	- 25-500Hz/15min, 10G, each 2 hours X, Y, Z	Each 2 hours	0/11
Solderability	JESD22-B102	- PbSn solder 215C,5S, (precon 93C 8hr)	5sec	0/11
		- Pb free solder, 245C, 5S,(precon 93C 8hr)	5sec	0/11

Electrical Characteristics Summary:

Electrical characteristics of qualification site matched to current production site.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
SNXH75M65L3F2STG	SNXH75M65L3F2STG
NXH027B120MNF2PTG	SNXH75M65L3F2STG